

HB

PATENT / DOCKET NO.: 24061.81 / TSMC2003-0440
CUSTOMER NO.: 27683

**INVENTOR'S DECLARATION FOR
PATENT APPLICATION**

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our names;

We believe we are the original, first and sole joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

**RAPID TEMPERATURE COMPENSATION MODULE
FOR SEMICONDUCTOR TOOL**

the specification of which: (check one)

 X is attached hereto.

 was filed on _____
under Attorney's Docket Number _____
as Application Serial No. _____
and was amended on _____ (if applicable).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the patentability of this application in accordance with 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

PATENT / DOCKET NO.: 24061.81 / TSMC2003-0440
CUSTOMER NO.: 27683

FULL NAME OF INVENTOR: Hsueh-Chang Wu

INVENTOR'S SIGNATURE: Hsueh-Chang Wu

DATED: 03/15/2004

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

FULL NAME OF INVENTOR: Chih-Tien Chang

INVENTOR'S SIGNATURE: Chih-Tien Chang

DATED: 01/27/2004

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

FULL NAME OF INVENTOR: Hsueh-Chang Wu

INVENTOR'S SIGNATURE: _____

DATED: _____

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

FULL NAME OF INVENTOR: Chih-Tien Chang

INVENTOR'S SIGNATURE: Chih-Tien Chang

DATED: 01/27/2004

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

FULL NAME OF INVENTOR: Jhi-Cherng Lu

INVENTOR'S SIGNATURE: Lu, Jhi-Cherng

DATED: Jan/17/2004

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

FULL NAME OF INVENTOR: Bing-Hung Chen

INVENTOR'S SIGNATURE: Bing-Hung, Chen

DATED: 2/19/2004

RESIDENCE: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

CITIZENSHIP: Citizen of Taiwan, R.O.C.

POST OFFICE ADDRESS: No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.


TO 0026567791691

P.03

15-MAR-2004 09:55 FROM

PATENT / DOCKET NO.: 24061.81 / TSMC2003-0440
CUSTOMER NO.: 27683

FULL NAME OF INVENTOR: Mei-Sheng Zhou

INVENTOR'S SIGNATURE: 

DATED: 3/16/2004

RESIDENCE:

~~No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.~~36 Verde Crescent
Singapore 688391

CITIZENSHIP:

~~Citizen of Taiwan, R.O.C.~~

Singapore

POST OFFICE ADDRESS:

No. 8, Li-Hsin Rd. 6
Hsin-Chu, Taiwan 300-77, R.O.C.

R-64113.1